

DNCC

Characteristics

1. Because of excellent resistance to solder temperature, it bears up against flow-soldering process and is used consequently for a wide range of parts of high-class electronic equipment.
2. Excellent heat resistance for a long period of time and less discoloration of adhesive.
3. Excellent migration resistance.
4. Least repellency.

Specifications for Standard Products

Thickness of base film (μm)		12.5,25,50
Adhesive	Classification	Thermosetting Resin
	Thickness (μm)	15,25,35
Releasing Materials on Adhesive Surface		Release Paper
Standard Size (μm)		500mmxRoll (100m)

Caution

1. Time and temperature rapidly promote a change from the semi-cured to the fully cured adhesive state, so keep coverlays at 5deg or below and at 80%RH or below.
2. Guaranteed period for DNCC before unpacked is 6 months after manufacture.
3. Moisture in press pads made of paper might make adhesiveness weaker and cause delamination of adhesive and polyimide film. If paper is used as press pads, be sure to check before using that no delamination occurs.

An Example of Processing Method

1. Setting at room temp.
2. Removing Air (about 5 times)
3. Apply pressure (2 to 40 kg/cm^2)
4. Temp. Elevation

5. Removing Air again at 100
6. Apply pressure (20 to 40 kg/ cm²)
7. Removing Air again at 140 to 160
8. Press-bonding at 160 under pressure of 20 to 40kg/ cm² for 40 to 60 min.
9. Cooling
10. Taking out

Examples of Characteristic Properties of DNCC

Test Item	Unit	Treatment conditions	Properties	Test methods
Resin Flow	mm	A	0.18	Our Standard
Surface resistance (RS)	Ω	C-96/20/65	3.0x10 ¹⁴	JIS-C-6481
		+96/40/90	8.0x10 ¹³	
Volume resistance (RS)	Ω-cm	C-96/20/65	1.0x10 ¹⁵	JIS-C-6471
		+96/40/90	5.0x10 ¹⁴	
Peel Strength	N/mm	A	0.7	JPCA-BM-02
		E-1/180	0.7	
Solder temp resistance		280/10sec.	NO change in appearance	IPC-FC-232B
Heat Resistance	-	E-24/130	NO change in appearance	JIS-C-6481
Chemical resistance		23/10 min.	NO change in appearance	JPCA-BM-02